



Soldering Reflow:

Preheat condition: 150 ~200°C / 60~120 sec.

Allowed time above 217°C: 60~90 sec.

Max temperature: 260°C.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

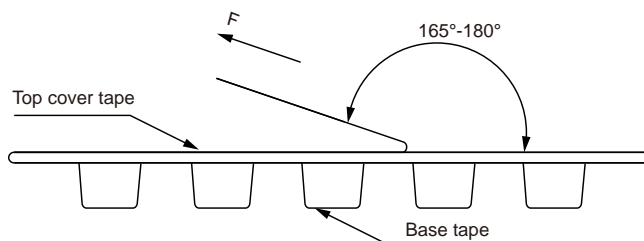


Packaging Information:

Tape Dimension:

| Series | A0 (mm) | B0 (mm) | D (mm) | P0 (mm) | P1 (mm) | W (mm) | K0 (mm) | E (mm) | T (mm) |
|----------|------------|------------|-----------|------------|------------|-----------|------------|-----------|-----------|
| MDTE7030 | 8.2±0.1 | 8.0±0.1 | 1.5±0.1 | 4.0±0.1 | 12.0±0.1 | 16.0±0.3 | 3.3±0.1 | 1.75±0.1 | 0.35±0.05 |

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N



Reel Dimension: [mm]



Packaging Quantity: